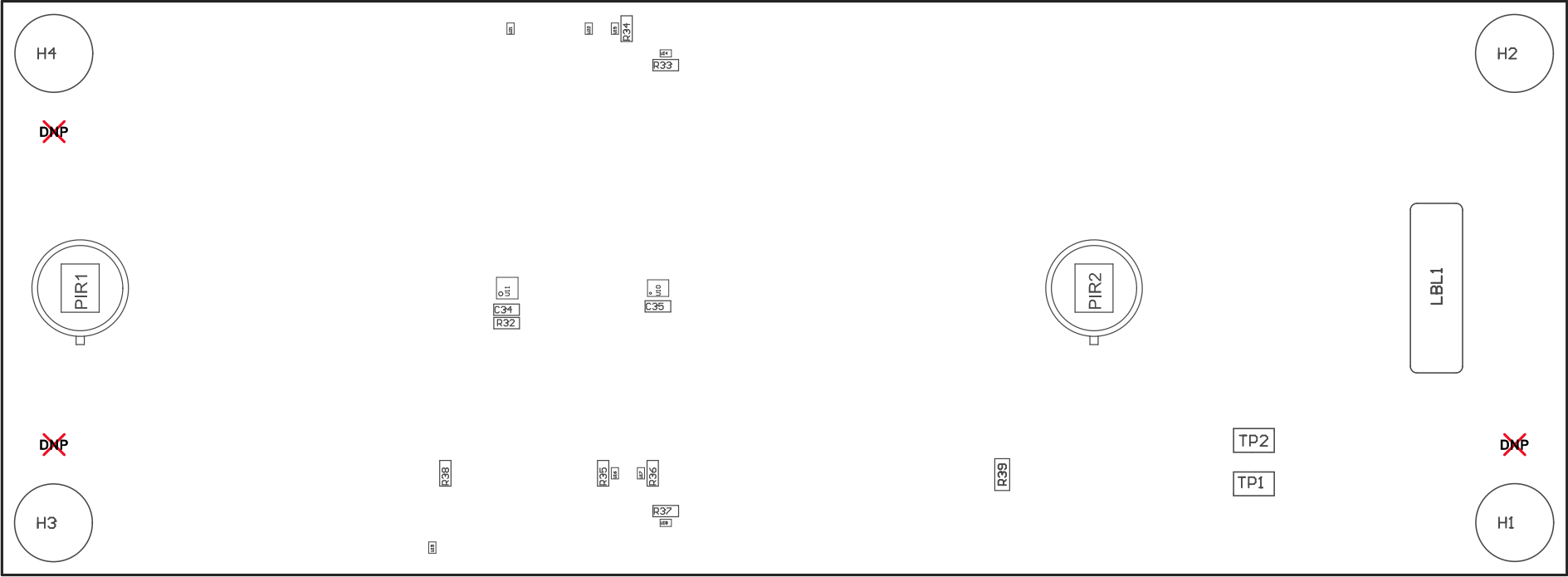


Z21 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22 ■These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
	TID #: 01069		
PLOT NAME = Top Assembly Drawing	GENERATED : 28/02/2017 11:10:50		TEXAS INSTRUMENTS

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